



Material Content Data Sheet



Sales Product Name				BSC100N03MS G		Issued		31. July 2018	
MA#				MA002843808					
Package				PG-TDSON-8-5		Weight*		123.51 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.709	0.57	0.57	5739	5739	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92		
	non noble metal	iron	7439-89-6	0.038	0.03		306		
	non noble metal	copper	7440-50-8	37.762	30.57	30.61	305728	306126	
	non noble metal	copper	7440-50-8	0.061	0.05	0.05	491	491	
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	491	491	
encapsulation	organic material	carbon black	1333-86-4	0.097	0.08		787		
	plastics	epoxy resin	-	6.904	5.59		55894		
	inorganic material	silicondioxide	60676-86-0	41.617	33.69	39.36	336942	393623	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.18	1.18	11753	11753	
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1340	1340	
solder	non noble metal	tin	7440-31-5	0.021	0.02		169		
	noble metal	silver	7440-22-4	0.026	0.02		211		
	non noble metal	lead	7439-92-1	0.996	0.81	0.85	8065	8445	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	iron	7439-89-6	0.011	0.01		92		
	non noble metal	copper	7440-50-8	11.320	9.16	9.17	91650	91770	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		54		
	non noble metal	iron	7439-89-6	0.022	0.02		181		
	non noble metal	copper	7440-50-8	22.292	18.05	18.08	180478	180713	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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